

| Thermal Characteristics                  |              |                     |     |     |       |  |  |  |
|--|--------------|---------------------|-----|-----|-------|--|--|--|
| Parameter                                |              | Symbol              | Тур | Max | Units |  |  |  |
| Maximum Junction-to-Ambient A            | t ≤ 10s      | R <sub>0JA</sub>    | 31  | 40  | °C/W  |  |  |  |
| Maximum Junction-to-Ambient <sup>A</sup> | Steady-State | κ <sub>θJA</sub>    | 59  | 75  | °C/W  |  |  |  |
| Maximum Junction-to-Lead <sup>C</sup>    | Steady-State | $R_{	ext{	hetaJL}}$ | 16  | 24  | °C/W  |  |  |  |

## Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)

| Symbol                 | Parameter                             | Conditions  | Min | Тур  | Max | Units |
|------------------------|---------------------------------------|---|-----|------|-----|-------|
| STATIC I               | PARAMETERS                            | ·   | ·   |      |     |       |
| BV <sub>DSS</sub>      | Drain-Source Breakdown Voltage        | I <sub>D</sub> =250μA, V <sub>GS</sub> =0V                        | 30  |      |     | V     |
| I <sub>DSS</sub> Z     | Zero Gate Voltage Drain Current       | V <sub>DS</sub> =24V, V <sub>GS</sub> =0V                         |     |      | 1   | μA    |
|                        |                                       | T <sub>J</sub> =55°0  | 5°C |      | 5   |       |
| I <sub>GSS</sub>       | Gate-Body leakage current             | $V_{DS}$ =0V, $V_{GS}$ = ±12V                                     |     |      | 100 | nA    |
| $V_{GS(th)}$           | Gate Threshold Voltage                | $V_{DS}=V_{GS}$ $I_{D}=250\mu A$                                  | 1   | 1.8  | 3   | V     |
| I <sub>D(ON)</sub>     | On state drain current                | V <sub>GS</sub> =4.5V, V <sub>DS</sub> =5V                        | 30  |      |     | Α     |
| R <sub>DS(ON)</sub> s  | Static Drain-Source On-Resistance     | V <sub>GS</sub> =10V, I <sub>D</sub> =8.5A                        |     | 22   | 26  | -mΩ   |
|                        |                                       | T <sub>J</sub> =12  | 5°C |      |     |       |
|                        |                                       | V <sub>GS</sub> =4.5V, I <sub>D</sub> =5A                         |     | 28   | 34  | mΩ    |
| <b>g</b> <sub>FS</sub> | Forward Transconductance              | V <sub>DS</sub> =5V, I <sub>D</sub> =5A                           |     |      |     | S     |
| $V_{SD}$               | Diode Forward Voltage                 | Is=1A,V <sub>GS</sub> =0V   |     | 0.76 | 1   | V     |
| I <sub>S</sub>         | Maximum Body-Diode Continuous Current |   |     |      | 4   | А     |
| DYNAMI                 | C PARAMETERS                          |   |     |      |     |       |
| C <sub>iss</sub>       | Input Capacitance                     |   |     | 590  |     | pF    |
| C <sub>oss</sub>       | Output Capacitance                    | V <sub>GS</sub> =0V, V <sub>DS</sub> =15V, f=1MHz                 |     | 162  |     | pF    |
| C <sub>rss</sub>       | Reverse Transfer Capacitance          |   |     | 40   |     | pF    |
| R <sub>g</sub>         | Gate resistance                       | V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1MHz                  |     | 0.45 |     | Ω     |
| SWITCHI                | NG PARAMETERS                         |   |     |      |     |       |
| Q <sub>g</sub>         | Total Gate Charge                     |   |     | 6.04 |     | nC    |
| Q <sub>gs</sub>        | Gate Source Charge                    | V <sub>GS</sub> =4.5V, V <sub>DS</sub> =15V, I <sub>D</sub> =8.5A |     | 1.46 |     | nC    |
| Q <sub>gd</sub>        | Gate Drain Charge                     |   |     | 2.56 |     | nC    |
| t <sub>D(on)</sub>     | Turn-On DelayTime                     |   |     | 3.7  |     | ns    |
| t <sub>r</sub>         | Turn-On Rise Time                     | V <sub>GS</sub> =10V, V <sub>DS</sub> =15V, R <sub>L</sub> =1.8Ω  | ,   | 3.5  |     | ns    |
| t <sub>D(off)</sub>    | Turn-Off DelayTime                    | $R_{GEN}=3\Omega$   |     | 14.9 |     | ns    |
| t <sub>f</sub>         | Turn-Off Fall Time                    |   |     | 2.5  |     | ns    |
| t <sub>rr</sub>        | Body Diode Reverse Recovery Time      | I <sub>F</sub> =5A, dI/dt=100A/μs                                 |     |      |     | ns    |
| Q <sub>rr</sub>        | Body Diode Reverse Recovery Charge    | I <sub>F</sub> =5A, dI/dt=100A/μs                                 |     |      |     | nC    |

A: The value of  $R_{0JA}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^{\circ}C$ . The value in any a given application depends on the user's specific board design. The current rating is based on the t ≤ 10s thermal resistance rating. B: Repetitive rating, pulse width limited by junction temperature.

C. The R  $_{\rm 0JA}$  is the sum of the thermal impedence from junction to lead R  $_{\rm 0JL}$  and lead to ambient.

D. The static characteristics in Figures 1 to 6 are obtained using  $80\mu$ s pulses, duty cycle 0.5% max.

E. These tests are performed with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^{\circ}C$ . The SOA curve provides a single pulse rating.